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| SERIAL NUMBER<br>10/806,521 | FILING DATE<br>03/23/2004<br><br>RULE | CLASS<br>438 | GROUP ART UNIT<br>2812 | ATTORNEY<br>DOCKET NO.<br>5649-1226 |
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APPLICANTS

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\*\* CONTINUING DATA \*\*\*\*\*  
*None WLL*

\*\* FOREIGN APPLICATIONS \*\*\*\*\*  
 REPUBLIC OF KOREA 2003-18275 03/24/2003 *WLL*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED  
 \*\* 08/25/2004

|  |  |   |                        |                       |                            |
|--|--|---|------------------------|-----------------------|----------------------------|
| Foreign Priority claimed<br>35 USC 119 (a-d) conditions met<br>Verified and Acknowledged | <input checked="" type="checkbox"/> yes <input type="checkbox"/> no<br><input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance<br><i>WLL</i><br>Examiner's Signature Initials | STATE OR<br>COUNTRY<br>KOREA,<br>REPUBLIC<br>OF | SHEETS<br>DRAWING<br>9 | TOTAL<br>CLAIMS<br>22 | INDEPENDENT<br>CLAIMS<br>4 |
|--|--|---|------------------------|-----------------------|----------------------------|

ADDRESS  
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TITLE  
 Methods of fabricating a semiconductor substrate for reducing wafer warpage

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|------------|---|--|
| FILING FEE | FEES: Authority has been given in Paper<br>No. _____ to charge/credit DEPOSIT ACCOUNT | <input type="checkbox"/> All Fees<br><input type="checkbox"/> 1.16 Fees ( Filing )<br><input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) |
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